



Material Content Data Sheet



Sales Product Name		BSC123N08NS3 G		Issued		25. January 2018		
MA#		MA001311890						
Package		PG-TDSON-8-5		Weight*		119.40 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.835	1.54	1.54	15367	15367
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		317	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	copper	7440-50-8	37.762	31.62	31.66	316261	316673
wire	non noble metal	copper	7440-50-8	0.062	0.05	0.05	523	523
encapsulation	organic material	carbon black	1333-86-4	0.085	0.07		713	
	plastics	epoxy resin	-	6.046	5.06		50639	
	inorganic material	silicondioxide	60676-86-0	36.448	30.53	35.66	305259	356611
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12158	12158
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1386	1386
solder	noble metal	silver	7440-22-4	0.046	0.04		385	
	non noble metal	tin	7440-31-5	0.037	0.03		308	
	non noble metal	lead	7439-92-1	1.758	1.47	1.54	14720	15413
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		95	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	copper	7440-50-8	11.320	9.48	9.49	94807	94930
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	iron	7439-89-6	0.022	0.02		187	
	non noble metal	copper	7440-50-8	22.292	18.67	18.70	186696	186939
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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